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VERSION WITH MARKINGS TO SHOW CHANGES MADE

1. (Three Times Amended) A semiconductor die assembly comprising:
 - a semiconductor die having a plurality of bond pads on an active surface thereof;
 - a lead frame having at least a first group of lead fingers and a second group of lead fingers to respectively extend from first and second opposing sides of said semiconductor die attached to a die-attach location on said lead frame to another, single side of said lead frame in a substantially mutually parallel configuration;
 - a first voltage reference plane to overlie in immediate proximity to therefrom, said first voltage reference plane overlying at least a turning portion of said first group of lead fingers extending from said first side of said [intended] die-attach location toward said another, single side of said lead frame; and
 - a second voltage reference plane to overlie in immediate proximity to said second group of lead fingers and in electrical isolation therefrom, said second voltage reference plane overlying at least a turning portion of said second group of lead fingers extending from said second opposing side of said [intended] die-attach location toward said another, single side of said lead frame. said first group of lead fingers and in electrical isolation

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